

## ABSTRACT

A method of fabricating a semiconductor package includes preparing a panel package including a redistribution substrate, a connection substrate and a plurality of lower semiconductor chips; sawing the panel package to form a plurality of separated strip packages each of which includes the sawed redistribution substrate, at least two of the lower semiconductor chips, and the sawed connection substrate; and providing a plurality of upper semiconductor chips on one of the strip packages to electrically connect the upper semiconductor chips to the sawed connection substrate.

FIG. 4E